

RELIABILITY REPORT FOR

DS1558, Rev A6

Dallas Semiconductor

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Prepared by:

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Conclusion:

The following qualification successfully meets the quality and reliability standards required of all Dallas Semiconductor products and processes:

In addition, Dallas Semiconductor's continuous reliability monitor program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards. The current status of the reliability monitor program can be viewed at http://www.maxim-ic.com/TechSupport/dsreliability.html.

Device Description:

A description of this device can be found in the product data sheet. You can find the product data sheet at http://dbserv.maxim-ic.com/l_datasheet3.cfm.

Reliability Derating:

The Arrhenius model will be used to determine the acceleration factor for failure mechanisms that are temperature accelerated.

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AfT = exp((Ea/k)*(1/Tu - 1/Ts)) = tu/ts

AfT = Acceleration factor due to Temperature

tu = Time at use temperature (e.g. 55°C)

ts = Time at stress temperature (e.g. 125°C)

k = Boltzmann's Constant (8.617 x 10-5 eV/°K)

Tu = Temperature at Use (°K)

Ts = Temperature at Stress (°K)
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Ea = Activation Energy (e.g. 0.7 ev)

The activation energy of the failure mechanism is derived from either internal studies or industry accepted standards, or activation energy of 0.7ev will be used whenever actual failure mechanisms or their activation energies are unknown. All deratings will be done from the stress ambient temperature to the use ambient temperature.

An exponential model will be used to determine the acceleration factor for failure mechanisms, which are voltage accelerated.

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AfV = exp(B*(Vs - Vu))

AfV = Acceleration factor due to Voltage

Vs = Stress Voltage (e.g. 7.0 volts)

Vu = Maximum Operating Voltage (e.g. 5.5 volts)

B = Constant related to failure mechanism type (e.g. 1.0, 2.4, 2.7, etc.)
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The Constant, B, related to the failure mechanism is derived from either internal studies or industry accepted standards, or a B of 1.0 will be used whenever actual failure mechanisms or their B are unknown. All deratings will be done from the stress voltage to the maximum operating voltage. Failure rate data from the operating life test is reported using a Chi-Squared statistical model at the 60% or 90% confidence level (Cf).

The failure rate, Fr, is related to the acceleration during life test by:

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Fr = X/(ts * AfV * AfT * N * 2)
X = Chi-Sq statistical upper limit
N = Life test sample size
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Failure Rates are reported in FITs (Failures in Time) or MTTF (Mean Time To Failure). The FIT rate is related to MTTF by:

MTTF = 1/Fr

NOTE: MTTF is frequently used interchangeably with MTBF.

The calculated failure rate for this device/process is:

FAILURE RATE: MTTF (YRS): 100592 FITS: 1.1

The parameters used to calculate this failure rate are as follows:

Cf: 60% Ea: 0.7 B: 0 Tu: 25 °C Vu: 5.5 Volts

The reliability data follows. A the start of this data is the device information. The next section is the detailed reliability data for each stress. The reliability data section includes the latest data available and may contain some generic data.

Device Information:

Process: D6N-1P2M,LLVt,ND cap PBL:GOI Passivation: Passivation w/Nov TEOS Oxide-Nitride

Die Size: 126 x 145

Number of Transistors: 0

Interconnect: Aluminum / 1% Silicon / 0.5% Copper

Gate Oxide Thickness: 150 Å

ELECTRICAL	CHARA	CTERIZATION
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DESCRIPTION	DATE CODE CONDITION		READPOINT		QTY	FAILS	FA#
ESD SENSITIVITY	0324	EOS/ESD S5.1 HBM 500 VOLTS	1	PUL'S	3	0	
ESD SENSITIVITY	0324	EOS/ESD S5.1 HBM 1000 VOLTS	1	PUL'S	3	0	
ESD SENSITIVITY	0324	EOS/ESD S5.1 HBM 2000 VOLTS	1	PUL'S	3	0	
ESD SENSITIVITY	0324	EOS/ESD S5.1 HBM 4000 VOLTS	1	PUL'S	3	3	No FA
ESD SENSITIVITY	0324	EOS/ESD S5.1 HBM 8000 VOLTS	1	PUL'S	3	3	No FA
LATCH-UP	0324	JESD78, I-TEST 125C	2	DYS	6	0	
LATCH-UP	0324	JESD78, Vsupply TEST 125C	2	DYS	6	0	
			,	Total:		6	

OPERATING LIFE							
DESCRIPTION	DATE COD	E CONDITION	REAL	POINT	QTY	FAILS	FA#
HIGH VOLTAGE LIFE	0028	125C, 6.0 VOLTS	1000	HRS	116	0	
HIGH VOLTAGE LIFE	0039	125C, 6.0 VOLTS	1000	HRS	116	0	
HIGH VOLTAGE LIFE	0208	125C, 6.0 VOLTS	1000	HRS	80	0	
HIGH VOLTAGE LIFE	0208	125C, 6.0 VOLTS	1000	HRS	80	0	
HIGH VOLTAGE LIFE	0208	125C, 6.0 VOLTS	1000	HRS	80	0	
HIGH VOLTAGE LIFE	0303	125C, 6.0 VOLTS	1000	HRS	77	0	
HIGH VOLTAGE LIFE	0303	125C, 6.0 VOLTS	1000	HRS	77	0	
HIGH TEMP OP LIFE	0324	125C, 5.5 VOLTS	988	HRS	77	0	

HIGH TEMP OP LIFE	0324	125C, 5.5 VOLTS		1000 HRS	77	0	
HIGH TEMP OP LIFE	0324	125C, 5.5 VOLTS		1000 HRS	77	0	
				Total:		0	
TEMPERATURE CY	CLE						_
DESCRIPTION	DATE CO	DDE CONDITION		READPOINT	QTY	FAILS	FA#
TEMP CYCLE	0028	-55C TO 125C		1000 CYS	77	0	
TEMP CYCLE	0039	-55C TO 125C		1000 CYS	77	0	
				Total:		0	
TEMPERATURE HU	MIDITY BI	AS					
DESCRIPTION	DATE CO	DDE CONDITION		READPOINT	QTY	FAILS	FA#
HAST	0028	130C, 85%R.H.,5.5V		100 HRS	77	0	
HAST	0039	130C, 85%R.H.,5.5V		100 HRS	77	0	
				Total:		0	
UNBIASED MOISTU	RE RESIS	TANCE					
DESCRIPTION	DATE CO	DATE CODE CONDITION		READPOINT	QTY	FAILS	FA#
AUTOCLAVE	0028	121C, 2 ATM STEAM, UNBIASED		168 HRS	45	0	
AUTOCLAVE	0039	121C, 2 ATM STEAM, UNBIASED		168 HRS	45	0	
				Total:		0	
FAILURE RATE:	N	MTTF (YRS): 100592	FITS:	1.1			